ID	WBS	Task Name	Duration	Start	Finish	Predecessors	MandS Items	Funding Category	Work Pkg
1	1.1	Run 2b Silicon	211.2 w	Mon 10/2/00	Wed 12/22/04				
2	1.1.1	Sensors	159.4 w	Mon 10/2/00	Tue 12/9/03				
33	1.1.1.2	L0 Sensors	59.2 w	Tue 10/1/02	Tue 12/9/03				
43	1.1.1.2.3	Production	59.2 w	Wed 10/2/02	Tue 12/9/03				
48	1.1.1.2.3.5	L0 Sensors Released For Production	0 w	Tue 4/22/03	Tue 4/22/03	47			
49	1.1.1.2.3.6	Produce L0 Sensors	20 w	Wed 4/23/03	Fri 9/12/03	48	1.1.1.2.3	EQ	
53	1.1.1.3	L1 Sensors	88.2 w	Mon 10/1/01	Thu 7/10/03				
69	1.1.1.3.2	Production	38.2 w	Wed 10/2/02	Thu 7/10/03				
76	1.1.1.3.2.7	Probe L1 sensors	12 w	Wed 4/16/03	Thu 7/10/03	71,75			
77	1.1.1.3.2.8	1st L1 Sensor Delivered	0 w	Tue 4/15/03	Tue 4/15/03	75			
101	1.1.2	Readout System	145 w	Tue 9/4/01	Mon 8/2/04				
102	1.1.2.1	SVX4 Chips	67 w	Mon 12/3/01	Thu 4/10/03				
111	1.1.2.1.9	All SVX4 Chips Produced And Tested	0 w	Thu 4/10/03	Thu 4/10/03	110			
239	1.1.2.11	L2-5 Junction Cards	78 w	Mon 1/7/02	Thu 7/24/03				
247	1.1.2.11.8	Test cards	16 w	Wed 4/2/03	Thu 7/24/03	246SS+4 w			
260	1.1.2.13	Adapter Cards	98 w	Tue 9/4/01	Thu 8/21/03				
268	1.1.2.13.8	Test cards	16 w	Wed 4/30/03	Thu 8/21/03	267			
291	1.1.2.15	Interface Boards And Low Voltage System	80.6 w	Mon 12/2/02	Thu 7/15/04				
294	1.1.2.15.3	Test prototypes	4 w	Wed 4/2/03	Tue 4/29/03	293			
295	1.1.2.15.4	Interface Boards Released For Modifications	0 w	Tue 4/29/03	Tue 4/29/03	294			
298	1.1.2.16	High-mass Cables	18 w	Thu 1/2/03	Wed 5/7/03				
300	1.1.2.16.2	Test new cables	2 w	Thu 4/24/03	Wed 5/7/03	299			
313	1.1.3	Mechanical Design and Fabrication	149.8 w	Mon 8/6/01	Fri 8/6/04				
320	1.1.3.2	South silicon barrel assembly	137.8 w	Mon 8/6/01	Wed 5/12/04				
321	1.1.3.2.1	L0-L1 barrel assembly	127 w	Mon 8/6/01	Thu 2/26/04				
322	1.1.3.2.1.1	L0 Barrel	127 w	Mon 8/6/01	Thu 2/26/04				
330	1.1.3.2.1.1.2	L0 structures	127 w	Mon 8/6/01	Thu 2/26/04				
345	1.1.3.2.1.1.2.15	Fabricate south layer 0 mechanical assemblies	6 w	Wed 4/16/03	Wed 5/28/03	343,344			
352	1.1.3.2.1.3	L1 Barrel	109.8 w	Mon 8/6/01	Thu 10/16/03				
353	1.1.3.2.1.3.1	L1 Readout module fixtures	50 w	Wed 10/16/02	Thu 10/16/03				
356	1.1.3.2.1.3.1.3	QC readout module fixtures	2 w	Tue 4/15/03	Mon 4/28/03	355			
357	1.1.3.2.1.3.1.4	Finalize readout module fabrication fixtures	2 w	Tue 4/29/03	Mon 5/12/03	356,142			
385	1.1.3.2.5	L2-L5 barrel assembly	109.2 w	Mon 10/1/01	Tue 12/9/03				
393	1.1.3.2.5.2	Staves	106.4 w	Mon 10/1/01	Mon 11/17/03				
395	1.1.3.2.5.2.2	Stave cores	78.6 w	Thu 11/1/01	Wed 6/4/03				
407	1.1.3.2.5.2.2.2	L4-L5 stave core fabrication	25 w	Mon 12/2/02	Wed 6/4/03				
410	1.1.3.2.5.2.2.2.3	Fabricate stave cores	6 w	Wed 4/2/03	Tue 5/13/03	409,448			
413	1.1.3.2.5.2.2.4	L2-L3 stave core fabrication	25 w	Mon 12/2/02	Wed 6/4/03				
416	1.1.3.2.5.2.2.4.3	Fabricate stave cores	6 w	Wed 4/2/03	Tue 5/13/03	415,448			
466	1.1.3.4	North silicon barrel assembly	70.8 w	Wed 3/5/03	Fri 7/30/04				
489	1.1.3.4.5	L2-L5 barrel assembly	63 w	Wed 3/5/03	Fri 6/4/04				
490	1.1.3.4.5.1	Staves	59.2 w	Wed 3/5/03	Fri 5/7/04				
513	1.1.3.4.5.1.3	Stave shells	8 w	Wed 3/5/03	Tue 4/29/03				
515	1.1.3.4.5.1.3.2	QC stave shells	3 w	Wed 4/9/03	Tue 4/29/03	514			
516	1.1.3.4.5.1.4	Stave Shells For North Complete	0 w	Tue 4/29/03	Tue 4/29/03	515			
535	1.1.3.8	Cylinders	110 w	Thu 11/29/01	Thu 2/19/04				
553	1.1.3.8.2	South extension cylinder	72.2 w	Thu 11/29/01	Wed 5/14/03				
562	1.1.3.8.2.9	Mate with south support cylinder assembly	0.2 w	Wed 4/30/03	Wed 4/30/03	552,561			
564	1.1.3.8.3	North support cylinder assembly	40 w	Wed 4/30/03	Thu 2/19/04				
565	1.1.3.8.3.1	Fabricate cylinder	12 w	Wed 4/30/03	Thu 7/24/03	552			
594	1.1.3.13	Prepare controls, monitoring, and interlocks	6 w	Wed 4/16/03	Wed 5/28/03	591,593	1.1.3.10,1.1.3.11	EQ	
597	1.1.4	Detector Production and Testing	130 w	Mon 10/29/01	Thu 6/10/04				
613	1.1.4.3	L1 Modules	67.6 w	Fri 5/10/02	Tue 9/16/03				
615	1.1.4.3.2	L1 Module Production Begun	0 w	Wed 4/30/03	Wed 4/30/03	616SS			
616	1.1.4.3.3	Align and glue sensors to hybrid	13 w	Wed 4/30/03	Thu 7/31/03	614,76SS+2 w,15			
619	1.1.4.3.6	Develop sensor module burn-in tests	2 w	Fri 4/25/03	Fri 5/9/03	621SF,598			
629	1.1.4.8	10/10 Axial Modules	69.4 w	Mon 7/1/02	Mon 11/17/03				
631	1.1.4.8.2	Develop sensor module burn-in tests	2 w	Wed 4/2/03	Tue 4/15/03	630,598	1.1.4.7(0.88)	EQ	
632	1.1.4.8.3	South	12.4 w	Tue 3/4/03	Thu 5/29/03				
636	1.1.4.8.3.4	10/10 South Axial Module Production Complete	0 w	Tue 4/29/03	Tue 4/29/03	635			
640	1.1.4.8.3.8	Perform quality assurance tests	7 w	Thu 4/10/03	Thu 5/29/03	639SS+2 w			
652	1.1.4.9	10/20 Axial Modules	63.4 w	Wed 10/23/02	Fri 2/6/04				
654	1.1.4.9.2	Develop sensor module burn-in tests	2 w	Wed 4/2/03	Tue 4/15/03	653,598			
675	1.1.4.10	20/20 Axial Modules	61.2 w	Wed 9/25/02	Tue 12/16/03				

ID	WBS	Task Name	Duration	Start	Finish	Predecessors	MandS Items	Funding Category	Work Pkg
677	1.1.4.10.2	Develop sensor module burn-in tests	2 w	Wed 4/2/03	Tue 4/15/03	676,598			
678	**1.1.4.10.3**	**South**	**11.2 w**	**Tue 4/8/03**	**Wed 6/25/03**				
679	**1.1.4.10.3.1**	**20/20 South Axial Module Production Begun**	**0 w**	**Tue 4/8/03**	**Tue 4/8/03**	**680SS**			
680	1.1.4.10.3.2	Align and glue sensors to hybrid	4 w	Tue 4/8/03	Mon 5/5/03	676,177SS+4 w,6			
681	1.1.4.10.3.3	Wirebond sensors to hybrid	4 w	Tue 4/22/03	Mon 5/19/03	680SS+2 w			
683	1.1.4.10.3.5	Debug sensor modules	4 w	Wed 4/23/03	Tue 5/20/03	681SS+1 d			
684	1.1.4.10.3.6	Burn-in sensor modules	4 w	Wed 4/30/03	Wed 5/28/03	683SS+1 w			
698	**1.1.4.11**	**10/10 Stereo Modules**	**70.2 w**	**Wed 9/25/02**	**Thu 2/26/04**				
700	1.1.4.11.2	Develop sensor module burn-in tests	2 w	Wed 4/2/03	Tue 4/15/03	699,598			
721	**1.1.4.12**	**10/20 Stereo Modules**	**57.6 w**	**Fri 12/20/02**	**Mon 2/23/04**				
723	1.1.4.12.2	Develop sensor module burn-in tests	2 w	Wed 4/2/03	Tue 4/15/03	722,598			
744	**1.1.4.13**	**20/20 Stereo Modules**	**62.2 w**	**Wed 11/20/02**	**Thu 2/26/04**				
746	1.1.4.13.2	Develop sensor module burn-in tests	2 w	Wed 4/2/03	Tue 4/15/03	745,598			

Resource Names
ETO,PHYSU[20%]
ETO,PHYSU[20%]
ETU,PHYSU[20%],EEU[20%]
EEO,PHYSU
ETF,PHYSF[20%]
MEU,MTU,PHYSU[40%]
MEF[50%],DESF[25%],CMMT,PHYSF[30%],CMMS
PHYSF[200%],DESF[150%],MEF[150%]
MTF[150%],MEF[10%],DESF[10%]
MTF[150%],MEF[10%],DESF[10%]
MTF,PHYSF[25%]
PHYSF,MEF,MTF,CMMT[25%],LK,DESF[20%]
PHYSF,MEF,DESF[10%],MTF[150%]
PHYSF,MEF,MTF
MTF[25%],PHYSF[25%],CMMM,CMMT[25%]
PHYSU,EEU[20%],ModuleBurnInStand
PHYSU,EEU[20%],ModuleBurnInStand
PHYSU[50%],ETF[25%],SASEQTestStandF[50%]
PHYSU,EEU[20%]

Resource Names
PHYSU,EEU,MTU
PHYSF,CMMS[400%],CMMT,MTF
WBNDR,WBNDRT,PHYSF[25%],MTF[50%]
PHYSF,MTF,SASEQTestStandF
PHYSU[200%],ModuleBurnInStand
PHYSU,EEU[20%],MTO[20%]
PHYSU,EEU[20%],MTO[20%]
PHYSU,EEU[20%],MTO[20%]